



## IC Knowledge – MEMS Cost Model Supported Processes List

As of January 25, 2008 the following processes are included in the MEMS Cost Model.

The syntax is: wafer size (mm) – process type (surface or bulk) – company – process details. Where “Enter Steps” is displayed the user may create their own process by filling in a table for the number of times each different standard process step is used in the process flow.

1. 1.2" x 2.4" - Bulk - Quartz Gyroscope
2. 100mm - 2 Layer Poly
3. 100mm - Bulk Pressure Sensor
4. 100mm - Coventor RF Relay
5. 100mm - Electrosatic Motor
6. 100mm - Enter steps
7. 100mm - Floating Element Flow Sensor
8. 100mm - Ford Accelerometer
9. 100mm - IMEPKU - 2 layer poly
10. 100mm - Protein Sensor
11. 100mm - RF Relay
12. 100mm - SUMMiT - 3 poly layers
13. 100mm - SAW
14. 150mm - 2 Layer Poly
15. 150mm - Bosch Accelerometer
16. 150mm - Bosch Accelerometer with electronics
17. 150mm - Bulk Pressure Sensor
18. 150mm - Coventor RF Relay
19. 150mm - Electrostatic Motor
20. 150mm - Enter steps
21. 150mm - Floating Element Flow Sensor
22. 150mm - Infotonics Hybrid SOI
23. 150mm - Lear Tire Pressure Sensor
24. 150mm - MEMS Cap Metal MUMPS
25. 150mm - MEMS Cap Poly MUMPS
26. 150mm - MEMS Cap SOI MUMPS
27. 150mm - Protein Sensor
28. 150mm - RF Relay
29. 150mm - SUMMiT - 3 poly layers
30. 150mm - SAW
31. 200mm - 2 Layer Poly
32. 200mm - Bosch Accelerometer
33. 200mm - Bosch Accelerometer with electronics
34. 200mm - Bulk Pressure Sensor
35. 200mm - Coventor RF Relay

36. 200mm - Electrostatic Motor
37. 200mm - Enter steps
38. 200mm - Floating Element Flow Sensor
39. 200mm - MEMS Cap Metal MUMPS
40. 200mm - MEMS Cap Poly MUMPS
41. 200mm - MEMS Cap SOI MUMPS
42. 200mm - RF Relay
43. 200mm - SUMMiT - 3 poly layerspoly)